

T491C226M006AT

General Information

Series

Style

Dielectric

Description RoHS

Termination

AEC-Q200

Specifications

Shelf Life

MSL

T491, Tantalum, MnO2 Tantalum, 22 uF, 20%, 6.3 VDC, SMD, MnO2, Molded, 1.8 Ohms, 6032, Height Max = 2.8mm

T491

Yes

Tin

No

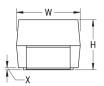
1

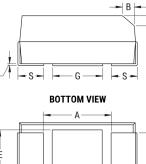
156 Weeks

MnO2 Tantalum SMD Chip

SMD, MnO2, Molded

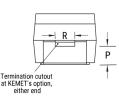
CATHODE (-) END VIEW





SIDE VIEW





Click here for the 3D model.

Footprint 6032 L 6mm +/-0.3mm W 3.2mm +/-0.3mm H 2.5mm +/-0.3mm T 0.13mm REF S 1.3mm +/-0.3mm F 2.2mm +/-0.1mm A 2.9mm MIN B 0.5mm +/-0.15mm G 2.4mm REF G 2.8mm REF P 0.9mm REF X 0.1mm +/-0.1mm	Dimensions	
W 3.2mm +/-0.3mm H 2.5mm +/-0.3mm T 0.13mm REF S 1.3mm +/-0.3mm F 2.2mm +/-0.1mm A 2.9mm MIN B 0.5mm +/-0.15mm G 2.8mm REF P 0.9mm REF R 0.9mm REF	Footprint	6032
H 2.5mm +/-0.3mm T 0.13mm REF S 1.3mm +/-0.3mm F 2.2mm +/-0.1mm A 2.9mm MIN B 0.5mm +/-0.15mm E 2.4mm REF G 2.8mm REF P 0.9mm REF R 1mm REF	L	6mm +/-0.3mm
T 0.13mm REF S 1.3mm +/-0.3mm F 2.2mm +/-0.1mm A 2.9mm MIN B 0.5mm +/-0.15mm E 2.4mm REF G 2.8mm REF P 0.9mm REF R 1mm REF	W	3.2mm +/-0.3mm
S 1.3mm +/-0.3mm F 2.2mm +/-0.1mm A 2.9mm MIN B 0.5mm +/-0.15mm E 2.4mm REF G 2.8mm REF P 0.9mm REF R 1mm REF	Н	2.5mm +/-0.3mm
F 2.2mm +/-0.1mm A 2.9mm MIN B 0.5mm +/-0.15mm E 2.4mm REF G 2.8mm REF P 0.9mm REF R 1mm REF	Т	0.13mm REF
A 2.9mm MIN B 0.5mm +/-0.15mm E 2.4mm REF G 2.8mm REF P 0.9mm REF R 1mm REF	S	1.3mm +/-0.3mm
B 0.5mm +/-0.15mm E 2.4mm REF G 2.8mm REF P 0.9mm REF R 1mm REF	F	2.2mm +/-0.1mm
E 2.4mm REF G 2.8mm REF P 0.9mm REF R 1mm REF	A	2.9mm MIN
G 2.8mm REF P 0.9mm REF R 1mm REF	В	0.5mm +/-0.15mm
P 0.9mm REF R 1mm REF	E	2.4mm REF
R 1mm REF	G	2.8mm REF
	Р	0.9mm REF
X 0.1mm +/-0.1mm	R	1mm REF
	Х	0.1mm +/-0.1mm

Т

	Capacitance	22 uF	
	Capacitance	20%	
	Tolerance	20%	
	Voltage DC	6.3 VDC (85C), 4.22 VDC (125C)	
	Temperature	-55/+125°C	
	Range		
	Rated	05%0	
	Temperature	85°C	
	Dissipation Factor	6% 120Hz 25C	

Dissipation Factor	5% IZUHZ 25C
Failure Rate	N/A
Resistance 1	.8 Ohms (100kHz 25C)
Ripple Current	247 mA (rms, 100kHz 25C), 222.3 mA (rms,
	35C), 98.8 mA (rms, 125C)
Leakage Current 1	.4 uA (5min 25°C)

Packaging Specifications	
Weight	224.48 mg
Packaging	T&R, 178mm
Packaging Quantity	500

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

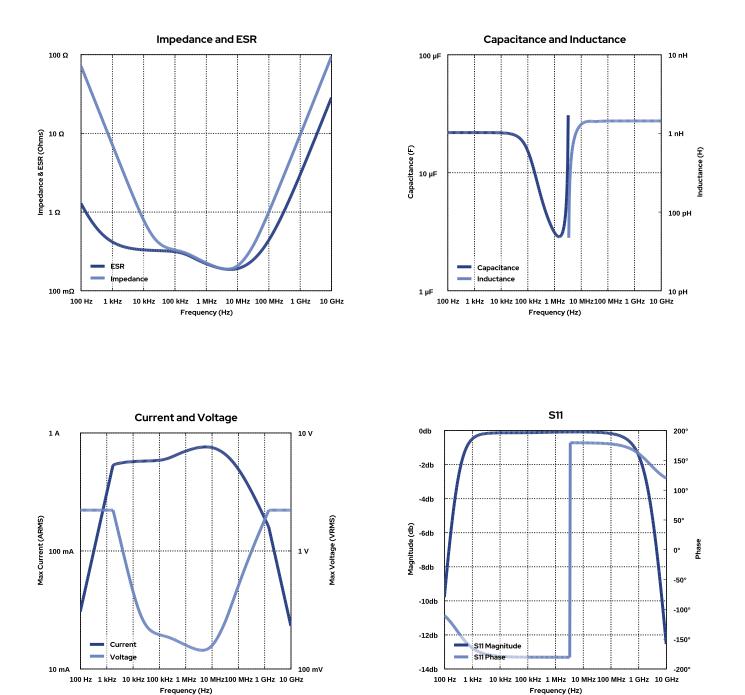


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Simulations

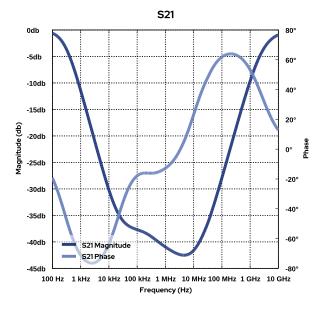
For the complete simulation environment please visit K-SIM.







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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
- The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages generated at any other harmonics.
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.